U.S. UTILITY Patent Application

	O.I.P.E.	PATENT DATE
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SCANNED LR² Q.A. AA		

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER T.D.
09/690600	D	029 257	780	2827	LUAN THAI

APPLICANTS

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TITLE

Solvent assisted burnishing of pre-underfilled solder bumped wafers for flipchip bonding

PTO-2040
12/99

ISSUING CLASSIFICATION

ORIGINAL			CROSS REFERENCE(S)						
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)						
INTERNATIONAL CLASSIFICATION									
					☐ Continued on Issue Slip Inside File Jacket				

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
☐ The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
	(Assistant Examiner)		(Date)		
☐ The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____				ISSUE FEE	
				Amount Due	Date Paid
	(Primary Examiner)		(Date)		
☐ The terminal ____ months of this patent have been disclaimed.				ISSUE BATCH NUMBER	
	(Legal Instruments Examiner)		(Date)		

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